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**Weekamp et al.**

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(54) **METHOD SUITABLE FOR TRANSFERRING A COMPONENT SUPPORTED BY A CARRIER TO A DESIRED POSITION ON A SUBSTRATE, AND A DEVICE DESIGNED FOR THIS**

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See application file for complete search history.

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(57)

#### **ABSTRACT**

A method for transferring an electronic component supported by a carrier to a desired position on a substrate include moving the carrier supporting the component relative to the substrate while the component is present on a side of the carrier facing towards the substrate, with the component is positioned opposite the desired position on the substrate. Then, a light beam is directed at the carrier, at the location of the component, from a side remote from the substrate, as a result of which a connection between the component and the carrier is broken and the component is transferred from the carrier to the substrate.

**12 Claims, 6 Drawing Sheets**

